

L Number	Hits	Search Text	DB	Time stamp
1	0	361/736.cccls. and 361/737.cccls. and 361/752.cccls. and 361/758.cccls. and 361/816.cccls. and 361/818.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 14:09
2	4943	361/736.cccls. or 361/737.cccls. or 361/752.cccls. or 361/758.cccls. or 361/816.cccls. or 361/818.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 14:10
3	44	(361/736.cccls. or 361/737.cccls. or 361/752.cccls. or 361/758.cccls. or 361/816.cccls. or 361/818.cccls.) and (card near (mold or encapsulant or encapsulate or epoxy or plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 15:08
4	35	((361/736.cccls. or 361/737.cccls. or 361/752.cccls. or 361/758.cccls. or 361/816.cccls. or 361/818.cccls.) and (card near (mold or encapsulant or encapsulate or epoxy or plastic))) and (@ad<20010611)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 14:13
5	25	((361/736.cccls. or 361/737.cccls. or 361/752.cccls. or 361/758.cccls. or 361/816.cccls. or 361/818.cccls.) and (card near (mold or encapsulant or encapsulate or epoxy or plastic))) and (@ad<20010611)) and (pcb or pwb or board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 14:53
6	1	("20020186549").PN.	USPAT;	2004/08/10 15:08
7	3183	(@ad<20010611) and (card near (mold or encapsulant or encapsulate or epoxy or plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 17:03
8	822	((@ad<20010611) and (card near (mold or encapsulant or encapsulate or epoxy or plastic))) and (cut or saw or singulate) and (card or mold or encapsulant or encapsulate or epoxy or plastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 16:09
9	4	6323064.URPN.	USPAT	2004/08/10 15:42
10	9	("4910582" "5280193" "5530289" "5635756" "5677246" "5877478" "5979772" "6049975" "6121681").PN.	USPAT	2004/08/10 15:44
11	8713	((frame or strip) and (cut or saw or singulate) and card and (mold or encapsulant or encapsulate or epoxy or plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 17:02
12	502	((frame or strip) and (cut or saw or singulate) and card and (mold or encapsulant or encapsulate or epoxy or plastic)) and (@ad<20010611) and (card near (mold or encapsulant or encapsulate or epoxy or plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 16:27
13	50	((frame or strip) and (cut or saw or singulate) and card and (mold or encapsulant or encapsulate or epoxy or plastic)) and (@ad<20010611) and (card near (mold or encapsulant or encapsulate or epoxy or plastic))) and mold (method or fabricating or fabrication) with (card or cards)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 16:22
14	48059	(method or fabricating or fabrication) near (card or cards)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 16:23
16	3763	(method or fabricating or fabrication) near (card or cards)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 16:24

17	311	((method or fabricating or fabrication) near (card or cards)) and ((chip or chips or die or dies) and strip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 16:25
18	122	((method or fabricating or fabrication) near (card or cards)) and ((chip or chips or die or dies) and strip)) and ((cut or saw or singulate) and card and (mold or encapsulant or encapsulate or epoxy or plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 16:26
19	81	((method or fabricating or fabrication) near (card or cards)) and ((chip or chips or die or dies) and strip)) and ((cut or saw or singulate) and card and (mold or encapsulant or encapsulate or epoxy or plastic))) and (@ad<20010611)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 16:54
20	1	("20020186549").PN.	USPAT; US-PGPUB	2004/08/10 17:01
21	1	("6483038").PN.	USPAT; US-PGPUB	2004/08/10 17:01
22	1057	(frame or strip or reel) and (cut or saw or singulate) and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:12
23	99	((frame or strip or reel) and (cut or saw or singulate) and card and (encapsulant or encapsulate or epoxy or plastic) and mold) and (@ad<20010611) and ((bend or force or move) with (tab or connecting or connector or tabs))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:05
24	25	257/666.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:16
25	17	(257/666.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold) and (@ad<20010611)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:18
26	7	438/15.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:17
27	11	438/125.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:17
28	1	438/25.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:17
29	0	438/26.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:17
30	26	438/106.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:18
31	1	438/51.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/10 17:18

32	0	438/55.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 17:18
33	2	438/64.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 17:18
34	13	(438/106.ccls. and card and (encapsulant or encapsulate or epoxy or plastic) and mold) and (@ad<20010611)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 17:19